Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: Form/Declaration Type: ti.com/support
Distribute - RoHS and IEC 62474 DB

Created on: 06/02/2022

Details for "LP2951CMMX"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LP2951CMMX	SNPB	Level-1-260C-UNLIM	Texas Instruments Electronics	DGK 8	3 x 3 x 1	30.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

Component Information

				Homogeneous Material Level		Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm		
Bond Wire									
Copper and Its Alloys	Copper	7440-50-8	0.02661	100	1000000	0.088299	883		
Sub-Total			0.02661	100	1000000	0.088299	883		
Die Attach Adhesive									
Precious Metals	Silver	7440-22-4	0.199862	74.999906	749999	0.663196	6632		
Thermoplastics	Ероху	85954-11-6	0.066621	25.000094	250001	0.221066	2211		
Sub-Total			0.266483	100	1000000	0.884262	8843		
Lead Frame									
Copper and Its Alloys	Copper	7440-50-8	14.618636	96.550003	965500	48.508572	485086		
Copper and Its Alloys	Iron	7439-89-6	0.360356	2.380001	23800	1.195758	11958		
Copper and Its Alloys	Phosphorus	7723-14-0	0.004542	0.029998	300	0.015072	151		
Precious Metals	Silver	7440-22-4	0.139297	0.919999	9200	0.462225	4622		
Zinc and Its Alloys	Zinc	7440-66-6	0.018169	0.119999	1200	0.06029	603		
Sub-Total			15.141	100	1000000	50.241917	502419		
Lead Frame Plating									
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.1725	15	150000	0.572401	5724		
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.9775	85	850000	3.243608	32436		
Sub-Total			1.15	100	1000000	3.81601	38160		
Mold Compound									
Other Inorganic Materials	Fused Silica	60676-86-0	11.379903	88.999999	890000	37.761584	377616		
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.383592	2.999998	30000	1.272862	12729		
Thermoplastics	Ероху	85954-11-6	1.022913	8.000003	80000	3.394301	33943		
Sub-Total			12.786408	100	1000000	42.428746	424287		
Semiconductor Device									
Ceramics / Glass	Doped Silicon	7440-21-3	0.76569	100	1000000	2.540766	25408		
Sub-Total			0.76569	100	1000000	2.540766	25408		
Total			30.136191			100	1000000		

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Tl bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Tl may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/02/2022

uctor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic require

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.